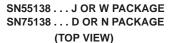
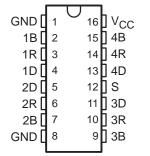
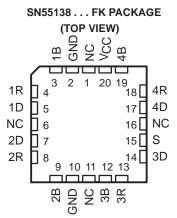
- Single 5-V Supply
- High-Input-Impedance, High-Threshold Receivers
- Common Driver Strobe
- TTL-Compatible Driver and Strobe Inputs With Clamp Diodes
- High-Speed Operation
- 100-mA Open-Collector Driver Outputs
- Four Independent Channels
- TTL-Compatible Receiver Output

description

The SN55138 and SN75138 quadruple bus transceivers are designed for two-way data communication over single-ended transmission lines. Each of the four identical channels consists of a driver with TTL inputs and a receiver with a TTL output. The driver open-collector output is designed to handle loads up to 100-mA open collector. The receiver input is internally connected to the driver output, and has a high impedance to minimize loading of the transmission line. Because of the high driver-output current and the high receiver-input impedance, a very large number (typically hundreds) of transceivers may be connected to a single data bus.







NC - No internal connection

The receiver design also features a threshold of 2.3 V (typical), providing a wider noise margin than would be possible with a receiver having the usual TTL threshold. A strobe turns off all drivers (high impedance) but does not affect receiver operation. These circuits are designed for operation from a single 5-V supply and include a provision to minimize loading of the data bus when the power-supply voltage is zero.

The SN55138 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN75138 is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Function Tables

TRANSMITTING

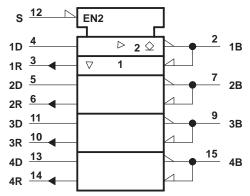
INP	UTS	OUTPUTS				
S	D	В	R			
L	Н	L	Н			
L	L	Н	L			

RECEIVING

	INPUTS	OUTPUT				
S	В	D	R			
Н	Н	Χ	L			
Н	L	Χ	Н			

H = high level, L = low level, X = irrelevant

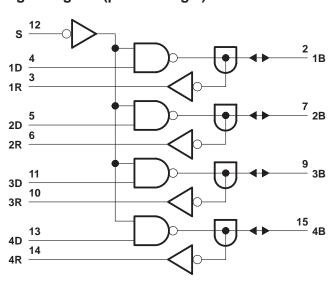
logic symbol†



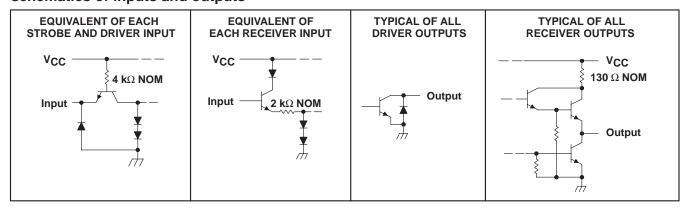
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)



schematics of inputs and outputs



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

,	Supply voltage, V _{CC} (see Note 1)	7 V
I	nput voltage, V _I	5.5 V
[Driver off-state output voltage	7 V
L	Low-level output current into the driver output	150 mA
(Continuous total dissipation See D	issipation Rating Table
(Operating free-air temperature range, T _A : SN55138	55°C to 125°C
	SN75138	0°C to 70°C
,	Storage temperature range, T _{stg}	65°C to 150°C
L	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D, N, or W package	260°C
	Case temperature for 60 seconds, T _C : FK package	
L	Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to both ground terminals connected together.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	_
FK‡	1375 mW	11.0 mW/°C	880 mW	275 mW
J‡	1375 mW	11.0 mW/°C	880 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	_
W	1000 mW	8.0 mW/°C	640 mW	200 mW

[‡] In the FK and J packages, the SN55138 chip is alloy mounted.

recommended operating conditions

		,	SN55138	;		SN75138		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5		5.5	4.75	5	5.25	V
High level input valtage V	Driver or strobe	2			2			V
High-level input voltage, VIH	Receiver	3.2			2.9			V
Law law liam to talkana M	Driver or strobe			0.8			0.8	V
Low-level input voltage, V _{IL}	Receiver			1.5			1.8	V
High-level output current, IOH	Receiver output			-400			-400	μΑ
Low lovel cutout current la	Driver output			100			100	A
Low-level output current, IOL	Receiver output			16			16	mA
Operating free-air temperature, TA		-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETE	D.			,	SN55138	3		SN75138	3	UNIT	
	PARAMETE	К	TEST CO	NDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII	
VIK	Input clamp voltage	Driver or strobe	V _{CC} = MIN,	I _I = -12 mA			-1.5			-1.5	V	
Vон	High-level output voltage	Receiver	V _{CC} = MIN, V _{IL} (R) = V _{IL} max,	VIH(S) = 2 V, I _{OH} = -400 μA	2.4	3.5		2.4	3.5		V	
\/ - ·	Low-level output	Driver	$V_{CC} = MIN,$ $V_{IL(S)} = 0.8 \text{ V},$	$V_{IH(D)} = 2 V$, $I_{OL} = 100 \text{ mA}$			0.45			0.45	V	
VOL	voltage	Receiver	$V_{CC} = MIN,$ $V_{IH(S)} = 2 V,$	$V_{IH(R)} = V_{IH}$ min, $I_{OL} = 16$ mA			0.4			0.4	V	
I _I (max)	Input current at maximum input voltage	Driver or strobe	V _{CC} = MAX,	VI = VCC			1			1	mA	
	High-level	Driver or strobe	V _{CC} = MAX,	V _I = 2.4 V			40			40	μΑ	
ΉΗ	input current	Receiver	V _{CC} = 5 V, V _I (S) = 2 V	$V_{I(R)} = 4.5 V,$		25	300		25	300	μΑ	
1	Low-level	Driver or strobe	V _{CC} = MAX,	V _I = 0.4 V		-1	-1.6		-1	-1.6	mA	
l _I IL	input current	Receiver	V _{CC} = MAX, V _I (S) = 2 V	$V_{I(R)} = 0.45 V,$			-50			-50	μΑ	
II(off)	Input current with power off	Receiver	V _{CC} = 0,	V _I = 4.5 V		1.1	1.5		1.1	1.5	mA	
los	Short-circuit output current§	Receiver	V _{CC} = MAX		-20		-55	-18		-55	mA	
	Supply	outputs low $V_{I(S)} = 0.8$	$V_{CC} = MAX,$ $V_{I(S)} = 0.8 V$	V _{I(D)} = 2 V,		50	65		50	65		
ICC	Supply current Al	All driver outputs high	V _{CC} = MAX, V _{I(S)} = 2 V, Receiver outputs or	$V_{I(R)} = 3.5 \text{ V},$		42	55		42	55	mA	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. Parenthetical letters D, R, and S used with V_I refer to the driver input, receiver input, and strobe input, respectively.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TI	EST CONDITIO	MIN	TYP	MAX	UNIT	
t _{PLH}	Driver	Driver	C 50 pF	R _L = 50 Ω,	See Figure 1		15	24	no
t _{PHL}	Dilvei	Dilvei					14	24	ns
t _{PLH}	Strobe	Driver	C[= 50 pr,				18	28	no
t _{PHL}	Strobe						22	32	ns
t _{PLH}	Receiver	Possivor	C 15 pE	Pt = 400 O	See Figure 2		7	15	20
t _{PHL}	Receiver	Receiver	C _L = 15 pF	$R_L = 400 \Omega$,	See Figure 2		8	15	ns

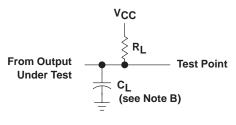
[¶] tp_{LH} = propagation delay time, low- to high-level output tp_{HL} = propagation delay time, high- to low-level output



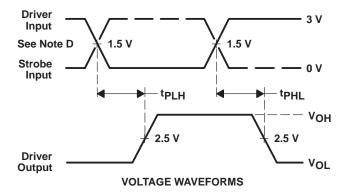
[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

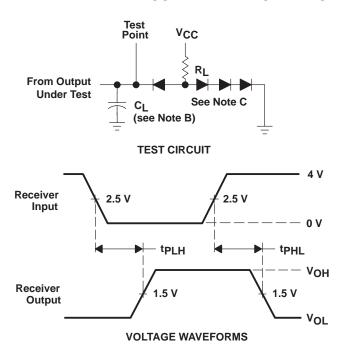


NOTES: A. Input pulses are supplied by generators having the following characteristics: t_W = 100 ns, PRR \leq 1 MHz, $t_f \leq$ 10 ns, $t_f \leq$

- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N916 or 1N3064.
- D. When testing driver input (solid line) strobe must be low; when testing strobe input (dashed line) driver input must be high.

Figure 1. Propagation Delay Times From Data and Strobe Inputs

PARAMETER MEASUREMENT INFORMATION



NOTES: A. Input pulses are supplied by generators having the following characteristics: t_W = 100 ns, PRR \leq 1 MHz, $t_f \leq$ 10 ns, $t_f \leq$

- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N916 or 1N3064.
- D. When testing driver input (solid line) strobe must be low; when testing strobe input (dashed line) driver input must be high.

Figure 2. Propagation Delay Times From Receiver Input



TYPICAL CHARACTERISTICS[†]

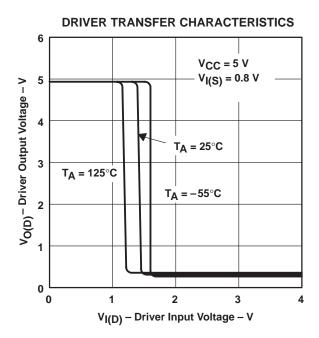
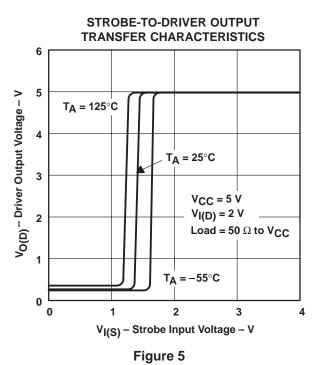


Figure 3



DRIVER TRANSFER CHARACTERISTICS

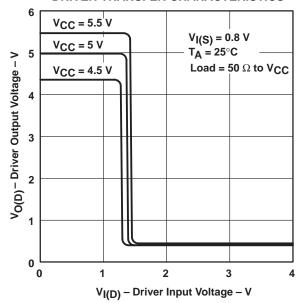


Figure 4

STROBE-TO-DRIVER OUTPUT TRANSFER CHARACTERISTICS

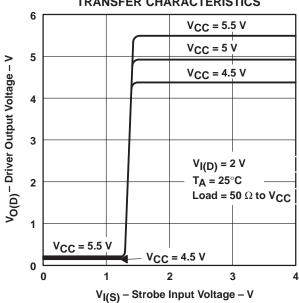


Figure 6

[†] Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.

TYPICAL CHARACTERISTICS[†]

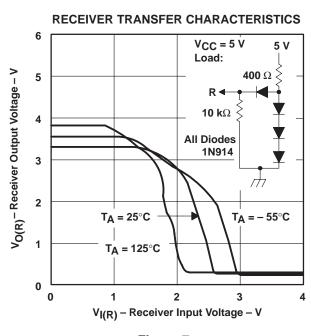
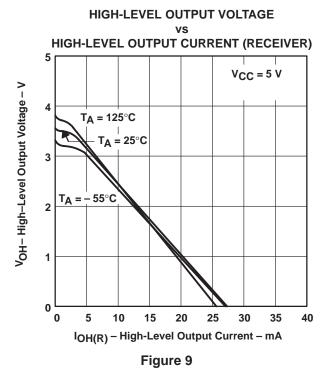


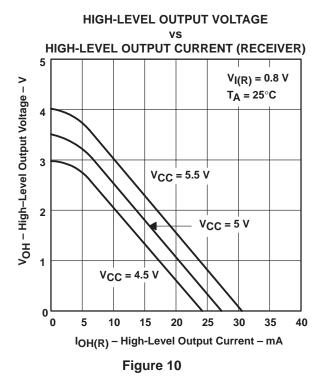
Figure 7



RECEIVER TRANSFER CHARACTERISTICS 6 T_A = 25°C 5 V Load: Vo(R) - Receiver Output Voltage - V 400 Ω 5 R ◀ $V_{CC} = 5.5 \text{ V}$ 10 $k\Omega$ 4 **VCC = 5 V All Diodes** 1N914 V_{CC} = 4.5 V 3 2 0

Figure 8

V_{I(R)} – Receiver Input Voltage – V



[†] Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.



V_CC = 5.5 V

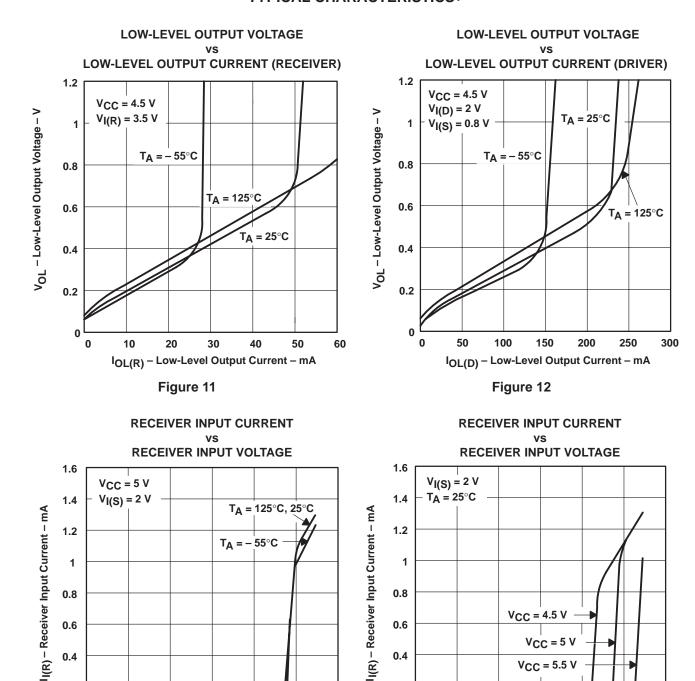
3

V_{I(R)} - Receiver Input Voltage - V

Figure 14

4

TYPICAL CHARACTERISTICS[†]



 $T_{\Delta} = 25^{\circ}C, -55^{\circ}C$

V_{I(R)} – Receiver Input Voltage – V

Figure 13

0.2

0

T_A = 125°C



6

0.2

0 0

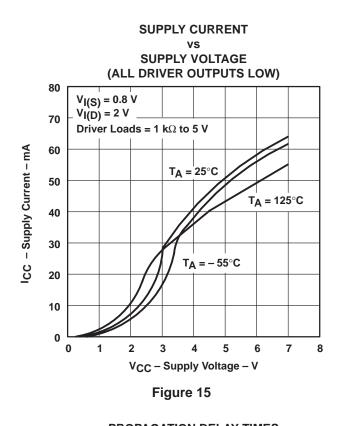
1

2

6

[†] Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.

TYPICAL CHARACTERISTICS[†]



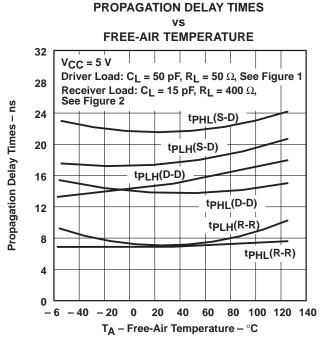


Figure 17

SUPPLY CURRENT SUPPLY VOLTAGE 80 T_A = 25°C $V_{I(S)} = 0.8 V$ 70 Driver Loads = 1 k Ω to 5 V R Output Open CC - Supply Current - mA 60 4 Driver Inputs at 2 V 50 2 Driver Inputs at 2 V, 2 Driver Inputs at 0.8 V 40 4 Driver Inputs at 0.8 V 30 20 10

Figure 16

3

0

0

PROPAGATION DELAY TIMES

V_{CC} - Supply Voltage - V

5

7

6

8

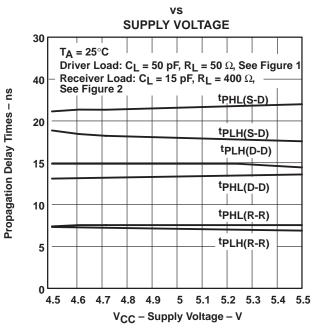
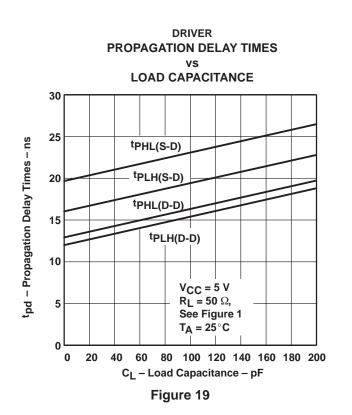


Figure 18

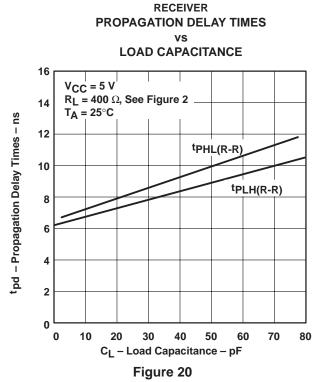
[†] Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.



TYPICAL CHARACTERISTICS



(B)



5 V 100 Ω 100 Ω 50 ft Belden #8795 100- Ω Telephone Cable ►(**D**) B (c)1/4 SN55138 1/4 SN55138 5 V 4 V 2 V (C) 2 V 0 V 5 V

APPLICATION INFORMATION

Figure 21. Point-to-Point Communication Over 50 Feet of Twisted Pair at 5 MHz

TYPICAL VOLTAGE WAVEFORMS

0 V

(D)

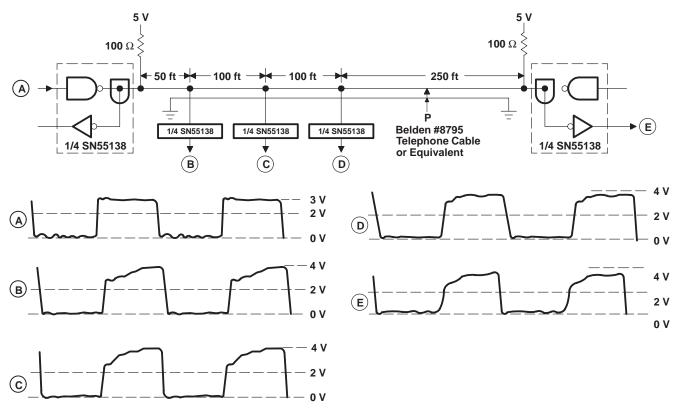


4 V

2 V

n v

APPLICATION INFORMATION



TYPICAL VOLTAGE WAVEFORMS

Figure 22. Party-Line Communication on 500 Feet of Twisted Pair at 1 MHz

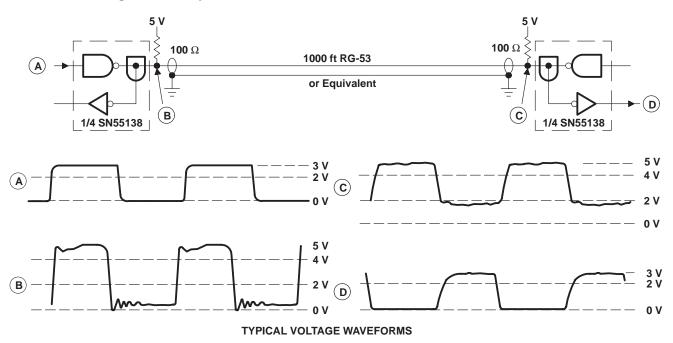


Figure 23. Point-to-Point Communication Over 1000 Feet of Coaxial Cable at 1 MHz



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN75138D	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75138	
SN75138DR	LIFEBUY	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75138	
SN75138N	LIFEBUY	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75138N	
SN75138NSR	LIFEBUY	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75138	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75138NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75138DR	SOIC	D	16	2500	340.5	336.1	32.0
SN75138NSR	SO	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type Pins		SPQ	L (mm)	W (mm)	T (µm)	B (mm)	
SN75138D	D	SOIC	16	40	507	8	3940	4.32	
SN75138N	N	PDIP	16	25	506	13.97	11230	4.32	



SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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